



Wafer & Device Packaging and Interconnect

Free Subscription

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Wafer & Device, Packaging and Interconnect
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A Do you wish to receive *Wafer & Device, Packaging and Interconnect* free of charge?

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Signature (required) Date _____

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Name (please print) _____

Title _____

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Company Name _____

Address _____

Please indicate: Home address Company address

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B What is your company's business?

Insert primary number description in this box
and check all others that apply

- 1. Semiconductor/MEMS Manufacturing
- 2. Communications Equipment or Consumer Electronics
- 3. Semiconductor or MEMS Packaging Foundry
- 4. CSP Manufacturing
- 5. Contract Manufacturing
- 6. Semiconductor/MEMS Equipment
- 7. Semiconductor/MEMS Test
- 8. Semiconductor/MEMS Materials
- 9. Military/Government
- 10. Industrial/Medical/Automotive
- 11. University or Research Organization
- 12. Other (please describe)

C Please indicate your primary job function. (check only one)

- 13. Assembly/Package Engineering
- 14. Corporate or General Management
- 15. Test Engineering
- 16. Engineering Management
- 17. IC/MEMS Design Engineering
- 18. Manufacturing Management
- 19. PC Board Design or Fabrication
- 20. Purchasing
- 21. R&D
- 22. Sales and Marketing
- 23. Consultant
- 24. Other (please describe)

D What products do you buy or specify?

PRODUCTION EQUIPMENT

- 25. Assembly Equipment/Materials for ICs/MEMS
- 26. Semiconductor/MEMS Packaging Foundry Services
- 27. Other Components
- 28. Design or Fabrication Services
- 29. Test Equipment
- 30. Inspection Equipment
- 31. Encapsulation Equipment, Mat'ls
- 32. Wire or Die Bonders
- 33. Sockets/Handlers
- 34. Wafer Bumping/Probing
- 35. Substrates/and interposers
- 36. Wafer-level packaging including TSVs, thinning, bonding, plating, deposition, etching

MATERIALS

- 36. Adhesives/Solder
- 37. Cleaning Solutions/Materials
- 38. Other (please describe)

- 39. None of the above

E What other publications are currently personally addressed to you? (Check all that apply.)

- 40. Advanced Packaging (digital or print)
- 41. Chip Scale Review
- 41. Circuits Assembly (digital or print)
- 42. Global SMT Packaging
- 43. MEPTec Report
- 44. Semiconductor Int'l. (digital or print)
- 45. SMT
- 46. Solid State Technology (digital or print)